

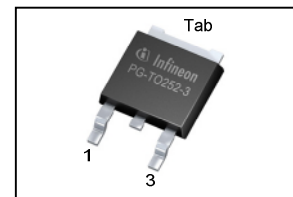
**OptiMOS™ -T2 Power-Transistor**

**Features**

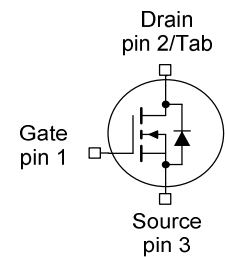
- N-channel - Enhancement mode
- AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green Product (RoHS compliant)
- 100% Avalanche tested

**Product Summary**

$V_{DS}$	80	V
$R_{DS(on),max}$	5.3	mΩ
$I_D$	90	A

**PG-TO252-3-313**


Type	Package	Marking
IPD90N08S4-05	PG-TO252-3-313	4N0805


**Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current <sup>1)</sup>	$I_D$	$T_C=25\text{ °C}, V_{GS}=10\text{V}$	90	A
		$T_C=100\text{ °C}, V_{GS}=10\text{V}^{2)}$	90	
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	$T_C=25\text{ °C}$	360	
Avalanche energy, single pulse <sup>2)</sup>	$E_{AS}$	$I_D=45\text{A}$	240	mJ
Avalanche current, single pulse	$I_{AS}$	-	75	A
Gate source voltage	$V_{GS}$	-	±20	V
Power dissipation	$P_{tot}$	$T_C=25\text{ °C}$	144	W
Operating and storage temperature	$T_j, T_{stg}$	-	-55 ... +175	°C

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
<b>Thermal characteristics<sup>2)</sup></b>						
Thermal resistance, junction - case	$R_{thJC}$	-	-	-	1.0	K/W
SMD version, device on PCB	$R_{thJA}$	minimal footprint	-	-	62	
		6 cm <sup>2</sup> cooling area <sup>3)</sup>	-	-	40	

**Electrical characteristics, at  $T_j=25^\circ\text{C}$ , unless otherwise specified**

### Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=1\text{mA}$	80	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=90\mu\text{A}$	2.0	3.0	4.0	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V, T_j=25^\circ\text{C}$	-	0.01	1	$\mu\text{A}$
		$V_{DS}=80V, V_{GS}=0V, T_j=125^\circ\text{C}^{2)}$	-	5	100	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=20V, V_{DS}=0V$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=90\text{A}$	-	4.5	5.3	m $\Omega$

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic characteristics<sup>2)</sup>**

Input capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=25V,$ $f=1MHz$	-	3600	4800	pF
Output capacitance	$C_{oss}$		-	1400	1860	
Reverse transfer capacitance	$C_{rss}$		-	75	150	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=40V, V_{GS}=10V,$ $I_D=90A, R_G=3.5\Omega$	-	12	-	ns
Rise time	$t_r$		-	7	-	
Turn-off delay time	$t_{d(off)}$		-	20	-	
Fall time	$t_f$		-	23	-	

**Gate Charge Characteristics<sup>2)</sup>**

Gate to source charge	$Q_{gs}$	$V_{DD}=64V, I_D=90A,$ $V_{GS}=0 \text{ to } 10V$	-	19	24	nC
Gate to drain charge	$Q_{gd}$		-	11	23	
Gate charge total	$Q_g$		-	52	68	
Gate plateau voltage	$V_{plateau}$		-	5.2	-	V

**Reverse Diode**

Diode continuous forward current <sup>2)</sup>	$I_S$	$T_C=25^\circ C$	-	-	90	A
Diode pulse current <sup>1)</sup>	$I_{S,pulse}$		-	-	360	
Diode forward voltage	$V_{SD}$	$V_{GS}=0V, I_F=90A,$ $T_j=25^\circ C$	-	0.95	1.3	V
Reverse recovery time <sup>1)</sup>	$t_{rr}$	$V_R=40V, I_F=50A,$ $di_F/dt=100A/\mu s$	-	93	-	ns
Reverse recovery charge <sup>1)</sup>	$Q_{rr}$		-	57	-	nC

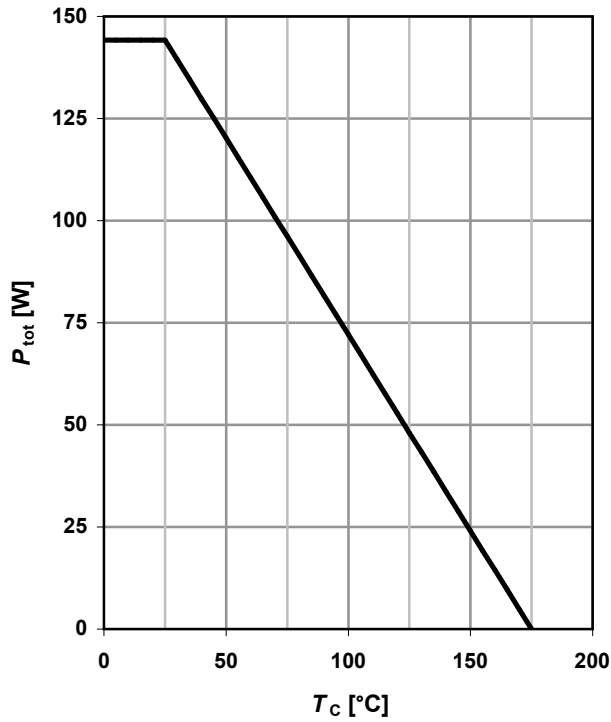
<sup>1)</sup> Current is limited by bondwire; with an  $R_{thJC} = 1K/W$  the chip is able to carry 120A at 25°C.

<sup>2)</sup> Specified by design. Not subject to production test.

<sup>3)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

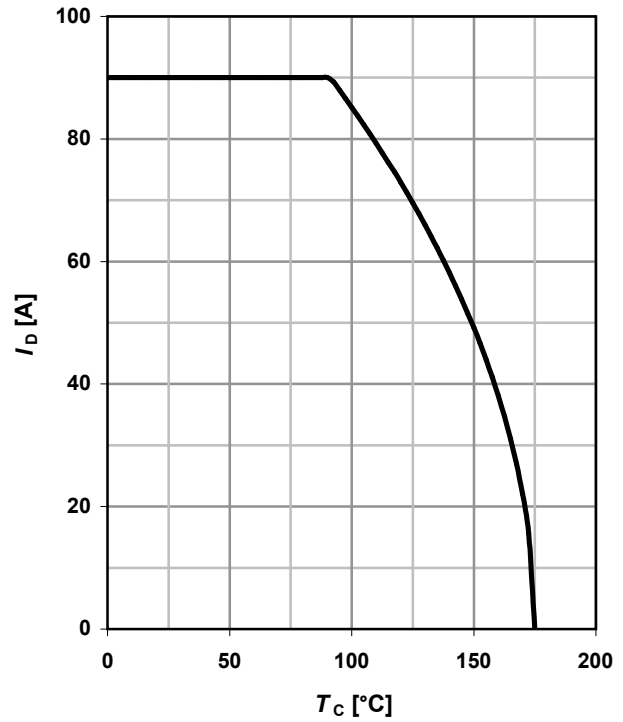
**1 Power dissipation**

$P_{tot} = f(T_C); V_{GS} \geq 6\text{ V}$



**2 Drain current**

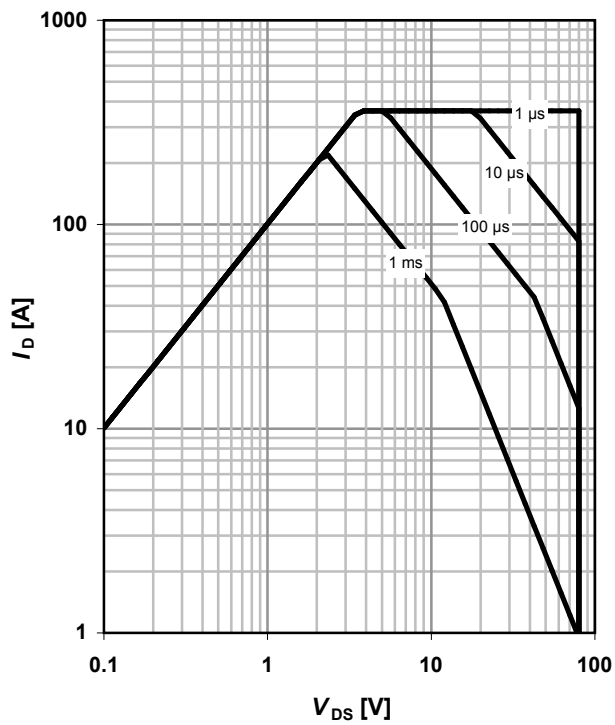
$I_D = f(T_C); V_{GS} = 10\text{ V}$



**3 Safe operating area**

$I_D = f(V_{DS}); T_C = 25\text{ °C}; D = 0$

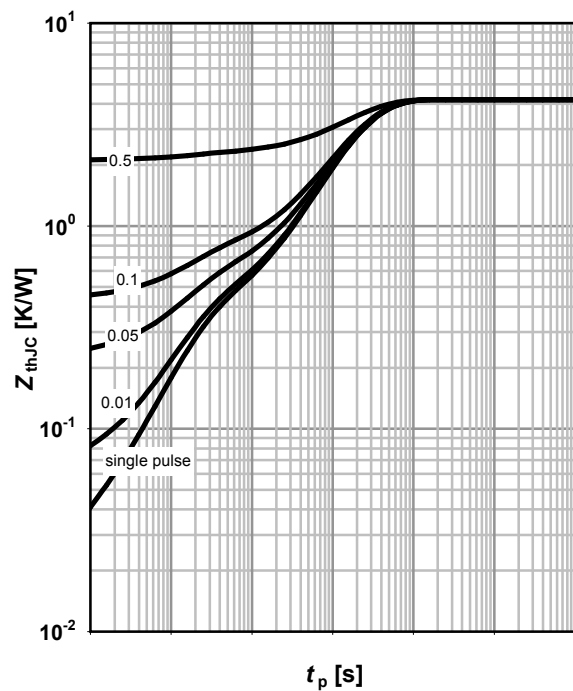
parameter:  $t_p$



**4 Max. transient thermal impedance**

$Z_{thJC} = f(t_p)$

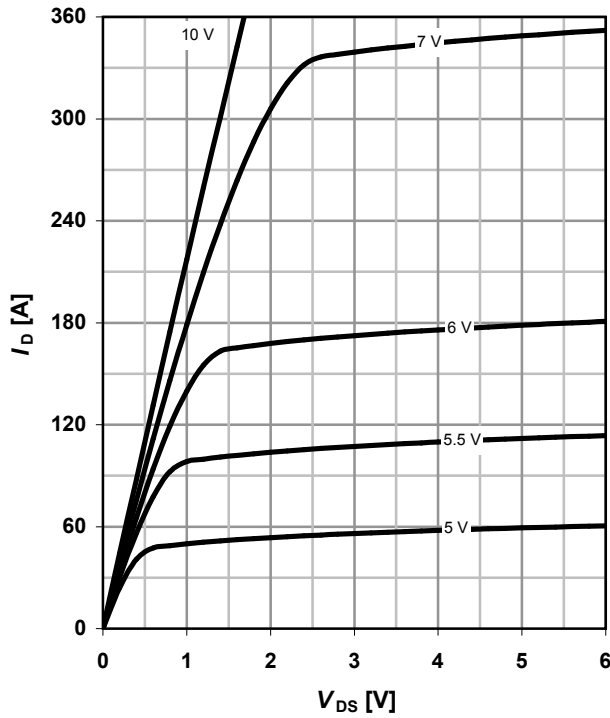
parameter:  $D = t_p/T$



**5 Typ. output characteristics**

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

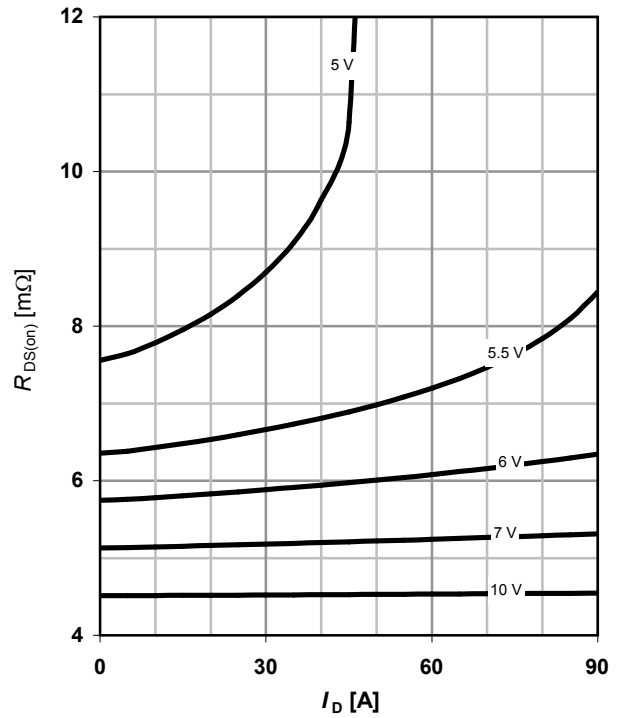
parameter:  $V_{GS}$



**6 Typ. drain-source on-state resistance**

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

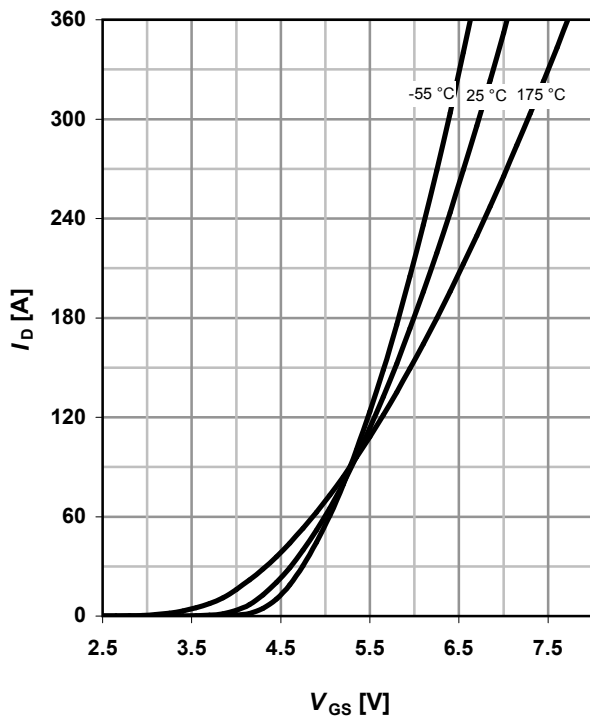
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

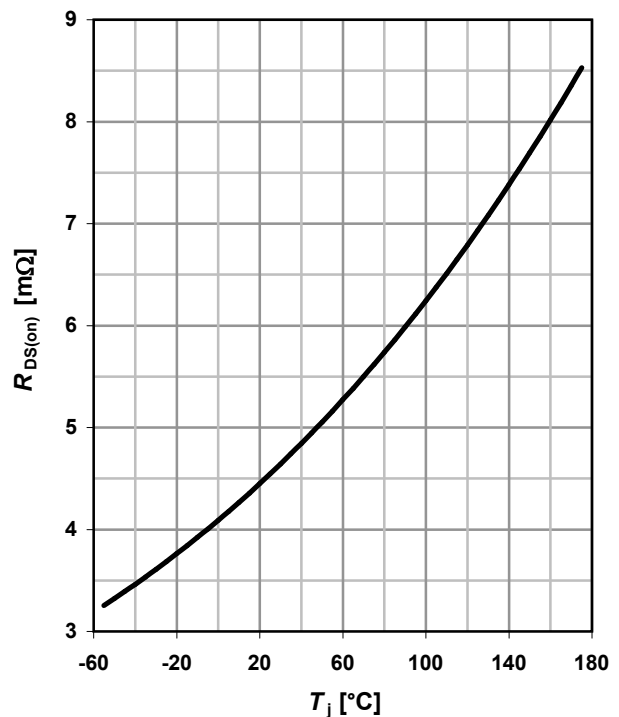
$I_D = f(V_{GS}); V_{DS} = 6\text{ V}$

parameter:  $T_j$



**8 Typ. drain-source on-state resistance**

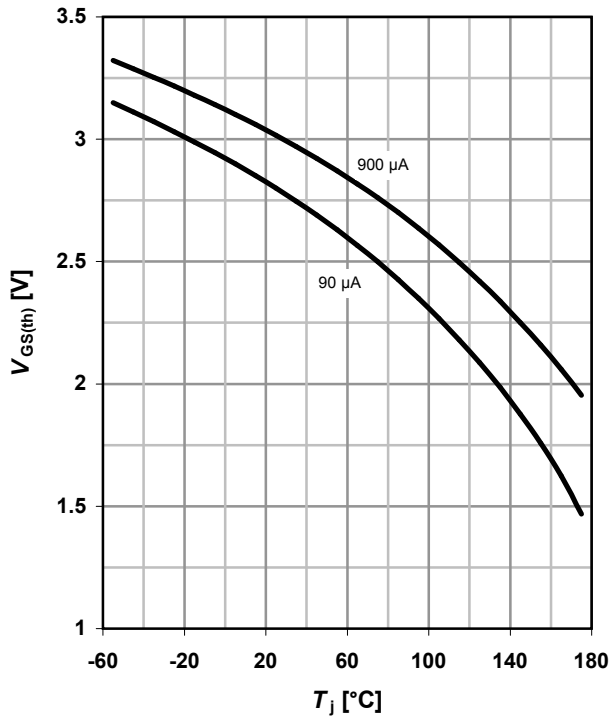
$R_{DS(on)} = f(T_j); I_D = 90\text{ A}; V_{GS} = 10\text{ V}$



**9 Typ. gate threshold voltage**

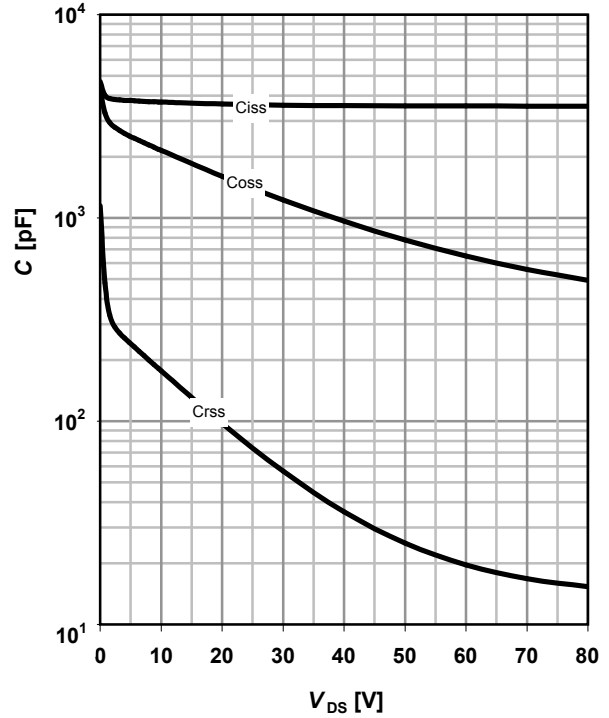
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter:  $I_D$



**10 Typ. capacitances**

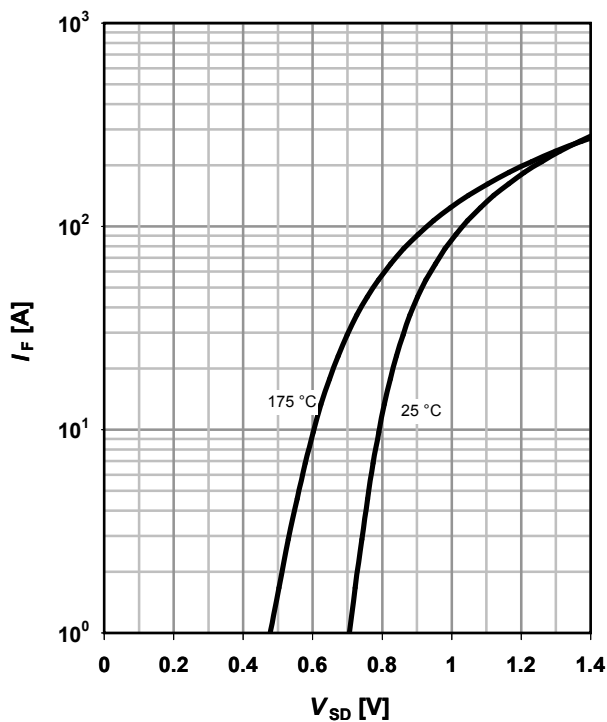
$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$



**11 Typical forward diode characteristics**

$I_F = f(V_{SD})$

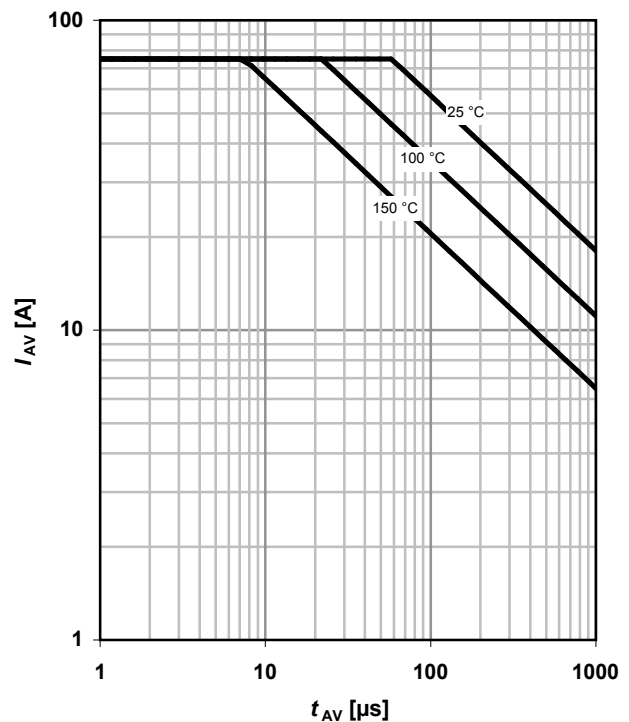
parameter:  $T_j$



**12 Avalanche characteristics**

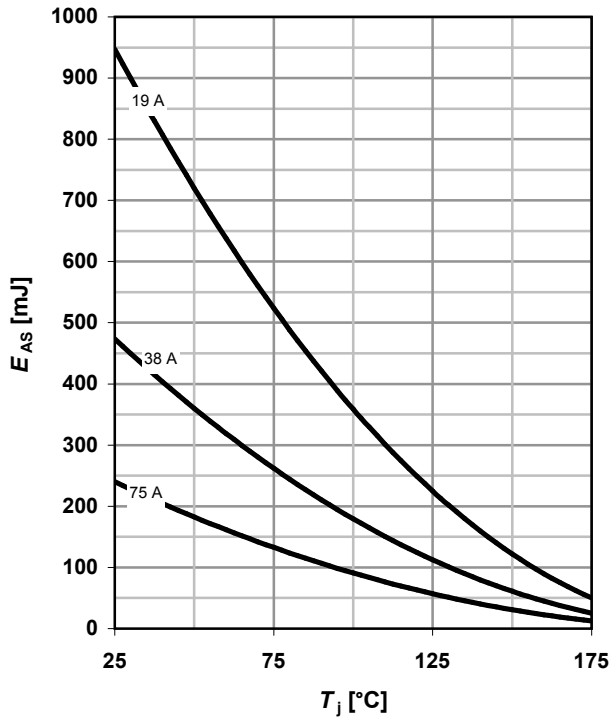
$I_{AS} = f(t_{AV})$

parameter:  $T_{j(start)}$



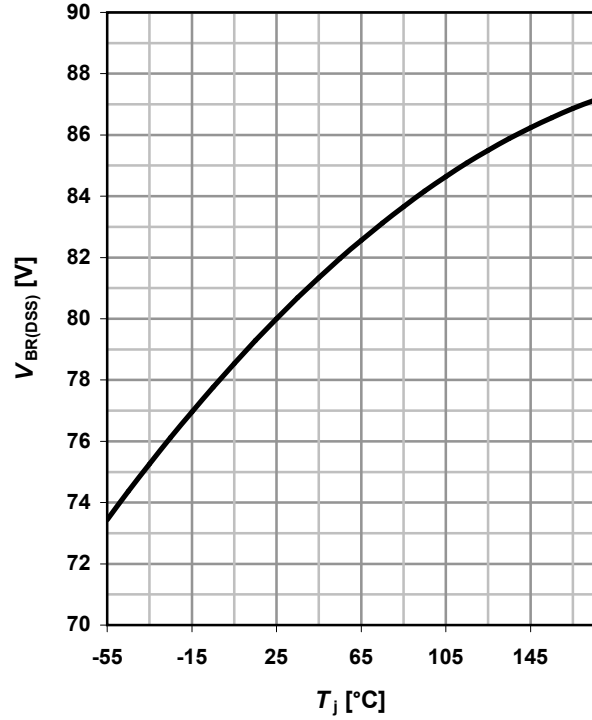
**13 Avalanche energy**

$$E_{AS} = f(T_j)$$



**14 Drain-source breakdown voltage**

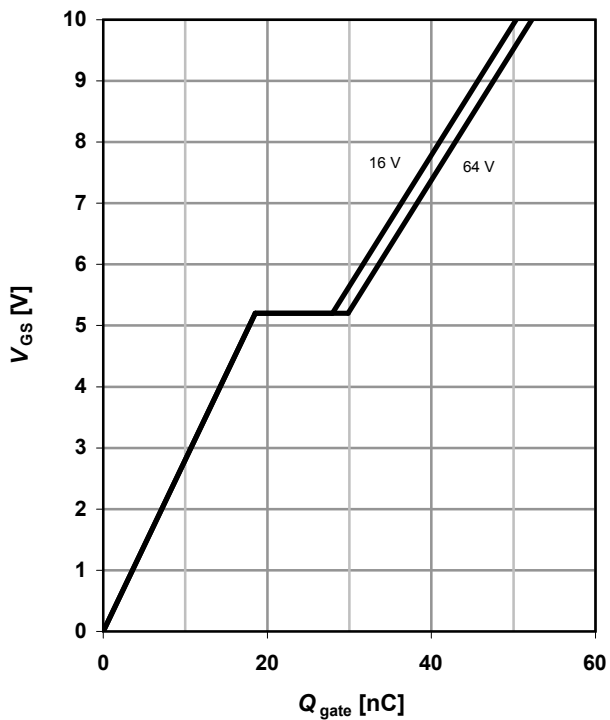
$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$



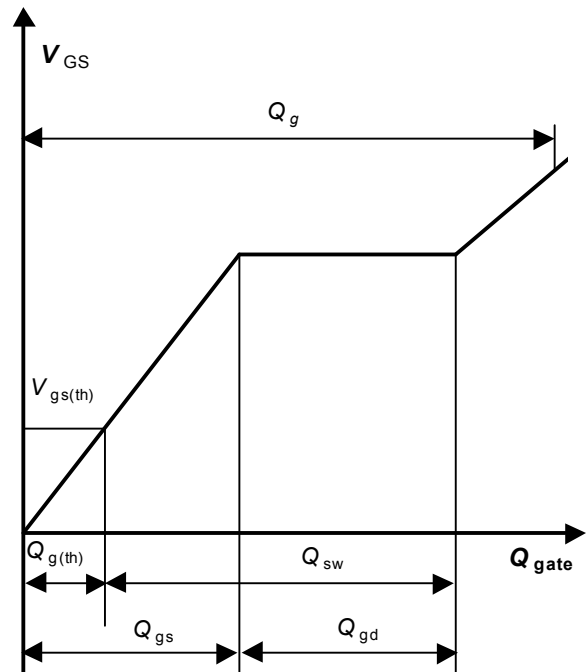
**15 Typ. gate charge**

$$V_{GS} = f(Q_{gate}); I_D = 90 \text{ A pulsed}$$

parameter:  $V_{DD}$



**16 Gate charge waveforms**



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## Revision History

Version	Date	Changes
Revision 1.0	20.06.2014	Final data sheet